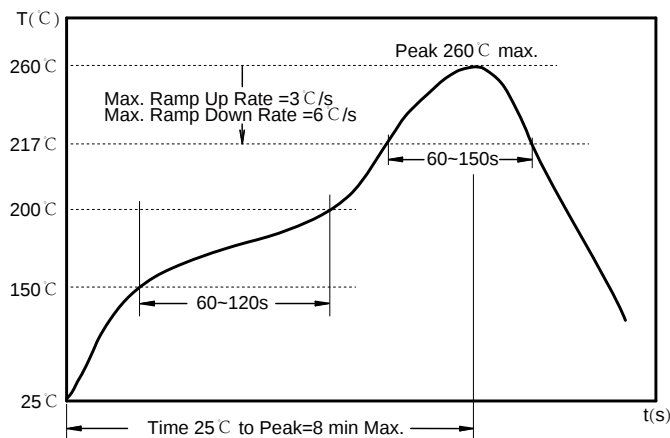


Soldering Reflow:



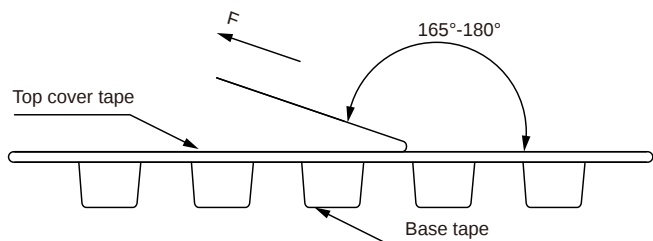
Preheat condition: $150 \sim 200^{\circ}\text{C}$ / 60~120 sec.
Allowed time above 217°C : 60~150 sec.
Max temperature: 260°C .
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension :

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
SCM9250	6.5 typ	9.7 typ	1.5 ± 0.1	4.0 ± 0.1	12.0 ± 0.1	16.0 ± 0.3	5.7 ref	1.75 ± 0.1	0.4 ± 0.1

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	Dot+Printing Duplex winding) /Printing Split winding)
---------	---

